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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	684
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	1152-BGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax2000-fg1152

1 – General Description

Axcelerator devices offer high performance at densities of up to two million equivalent system gates. Based upon the Microsemi AX architecture, Axcelerator has several system-level features such as embedded SRAM (with complete FIFO control logic), PLLs, segmentable clocks, chip-wide highway routing, and carry logic.

Device Architecture

AX architecture, derived from the highly-successful SX-A sea-of-modules architecture, has been designed for high performance and total logic module utilization (Figure 1-1). Unlike in traditional FPGAs, the entire floor of the Axcelerator device is covered with a grid of logic modules, with virtually no chip area lost to interconnect elements or routing.

Programmable Interconnect Element

The Axcelerator family uses a patented metal-to-metal antifuse programmable interconnect element that resides between the upper two layers of metal (Figure 1-2 on page 1-2). This completely eliminates the channels of routing and interconnect resources between logic modules (as implemented on traditional FPGAs) and enables the efficient sea-of-modules architecture. The antifuses are normally open circuit and, when programmed, form a permanent, passive, low-impedance connection, leading to the fastest signal propagation in the industry. In addition, the extremely small size of these interconnect elements gives the Axcelerator family abundant routing resources.

The very nature of Microsemi's nonvolatile antifuse technology provides excellent protection against design pirating and cloning (FuseLock technology). Typical cloning attempts are impossible (even if the security fuse is left unprogrammed) as no bitstream or programming file is ever downloaded or stored in the device. Reverse engineering is virtually impossible due to the difficulty of trying to distinguish between programmed and unprogrammed antifuses and also due to the programming methodology of antifuse devices (see "Security" on page 2-108).

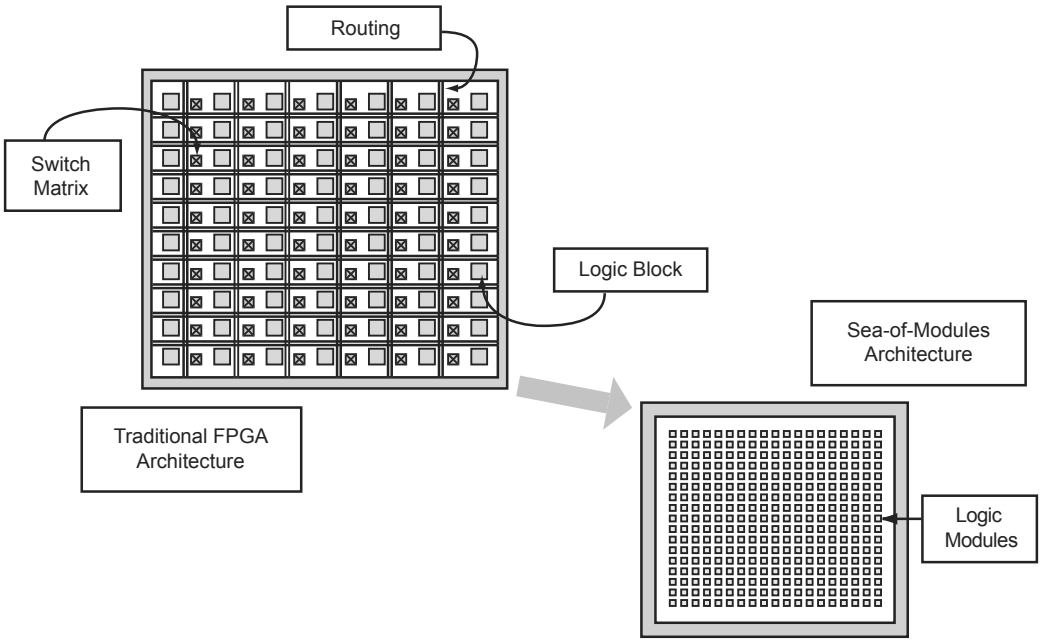


Figure 1-1 • **Sea-of-Modules Comparison**

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

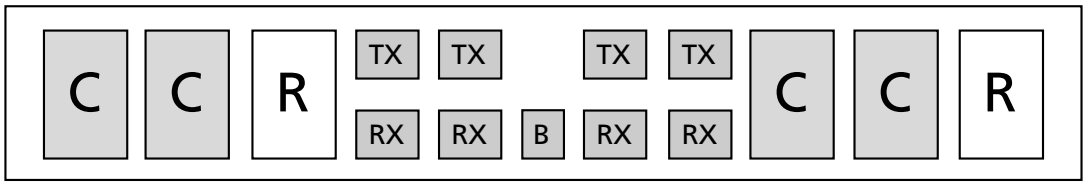


Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

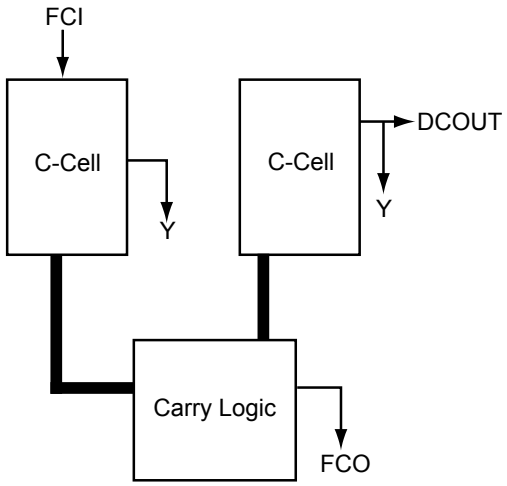


Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

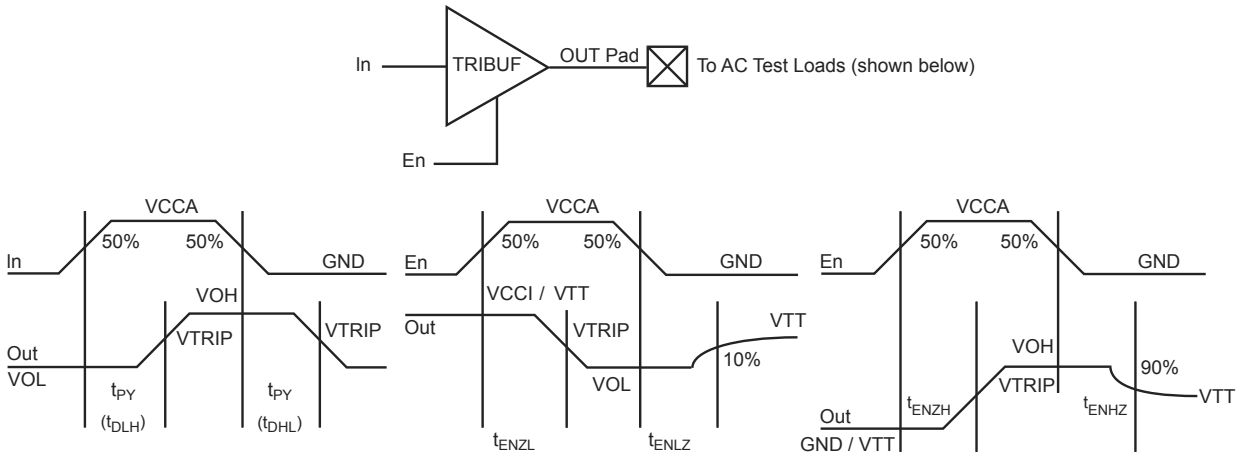


Figure 2-10 • **Output Buffer Delays**

Timing Model and Waveforms

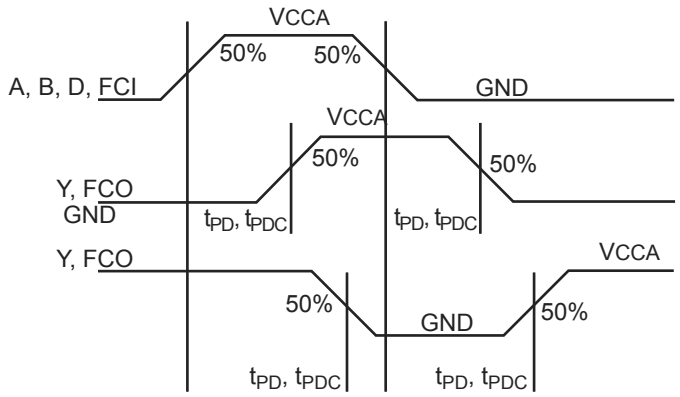


Figure 2-28 • **C-Cell Timing Model and Waveforms**

Timing Characteristics

Table 2-62 • **C-Cell**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
C-Cell Propagation Delays								
t_{PD}	Any input to output Y		0.74		0.84		0.99	ns
t_{PDC}	Any input to carry chain output (FCO)		0.57		0.64		0.76	ns
t_{PDB}	Any input through DB when one input is used		0.95		1.09		1.28	ns
t_{CCY}	Input to carry chain (FCI) to Y		0.61		0.69		0.82	ns
t_{CC}	Input to carry chain (FCI) to carry chain output (FCO)		0.08		0.09		0.11	ns

The HM and CM modules can select between:

- The HCLK or CLK source respectively
- A local signal routed on generic routing resources

This allows each core tile to have eight clocks independent of the other core tiles in the device.

Both HCLK and CLK are segmentable, meaning that individual branches of the global resource can be used independently.

Like the HM and CM modules, the HD and RD modules can select between:

- The HCLK or CLK source from the HM or CM module respectively
- A local signal routed on generic routing resources

The AX architecture is capable of supporting a large number of local clocks—24 segments per HCLK driving north-south and 28 segments per CLK driving east-west per core tile.

Microsemi's Designer software's place-and-route takes advantage of the segmented clock structure found in Axcelerator devices by turning off any unused clock segments. This results in not only better performance but also lower power consumption.

Global Resource Access Macros

Global resources can be driven by one of three sources: external pad(s), an internal net, or the output of a PLL. These connections can be made by using one of three types of macros: CLKBUF, CLKINT, and PLLCLK.

CLKBUF and HCLKBUF

CLKBUF (HCLKBUF) is used to drive a CLK (HCLK) from external pads. These macros can be used either generically or with the specific I/O standard desired (e.g. CLKBUF_LVCMOS25, HCLKBUF_LVDS, etc.) (Figure 2-42).

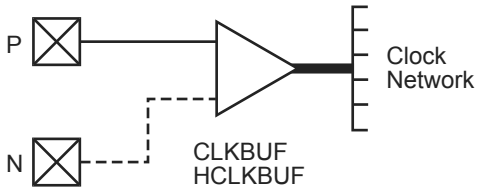


Figure 2-42 • **CLKBUF and HCLKBUF**

Package pins CLKEP and CLKEN are associated with CLKE; package pins HCLKAP and HCLKAN are associated with HCLKA, etc.

Note that when CLKBUF (HCLKBUF) is used with a single-ended I/O standard, it must be tied to the P-pad of the CLK (HCLK) package pin. In this case, the CLK (HCLK) N-pad can be used for user signals.

CLKINT and HCLKINT

CLKINT (HCLKINT) is used to access the CLK (HCLK) resource internally from the user signals (Figure 2-43).

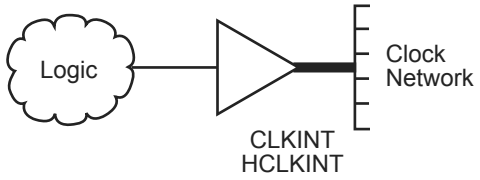


Figure 2-43 • **CLKINT and HCLKINT**

***Table 2-83* • South PLL Connections**

CLK1	CLK2
CLK1	Routed net
CLK1	Unused
CLK2	CLK1
CLK2	Routed net
CLK2	Both CLK1 and routed net
CLK2	Unused
Unused	CLK1
Unused	Routed net
Unused	Both CLK1 and routed net
Unused	Unused
Routed net	CLK1
Routed net	Unused
Both CLK1 and CLK2	Routed net
Both CLK1 and CLK2	Unused
Both CLK1 and routed net	Unusable
Both CLK2 and routed net	CLK1
Both CLK2 and routed net	Unused
CLK1, CLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g., CLK1 driving both CLK1 and CLK2 is not supported).

Embedded Memory

The AX architecture provides extensive, high-speed memory resources to the user. Each 4,608 bit block of RAM contains its own embedded FIFO controller, allowing the user to configure each block as either RAM or FIFO.

To meet the needs of high performance designs, the memory blocks operate in synchronous mode for both read and write operations. However, the read and write clocks are completely independent, and each may operate up to and above 500 MHz.

No additional core logic resources are required to cascade the address and data buses when cascading different RAM blocks. Dedicated routing runs along each column of RAM to facilitate cascading.

The AX memory block includes dedicated FIFO control logic to generate internal addresses and external flag logic (FULL, EMPTY, AFULL, AEMPTY). Since read and write operations can occur asynchronously to one another, special control circuitry is included to prevent metastability, overflow, and underflow. A block diagram of the memory module is illustrated in Figure 2-57.

During RAM operation, read (RA) and write (WA) addresses are sourced by user logic and the FIFO controller is ignored. In FIFO mode, the internal addresses are generated by the FIFO controller and routed to the RAM array by internal MUXes. Enables with programmable polarity are provided to create upper address bits for cascading up to 16 memory blocks. When cascading memory blocks, the bussed signals WA, WD, WEN, RA, RD, and REN are internally linked to eliminate external routing congestion.

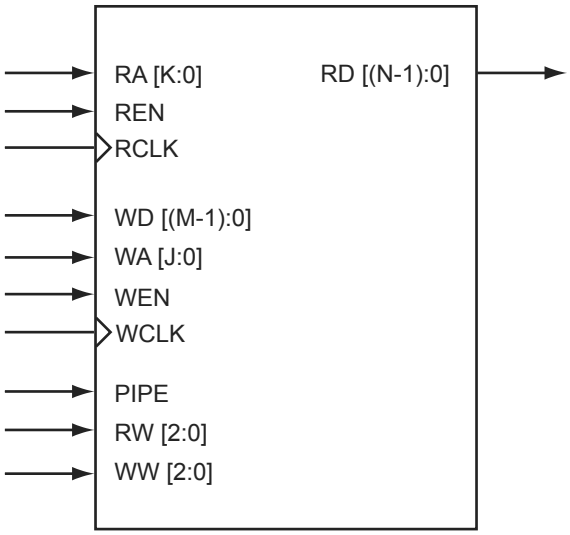


Figure 2-57 • **Axcelerator Memory Module**

***Table 2-89* • One RAM Block**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.22		0.25		0.30	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.08		1.23		1.45	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.22		0.25		0.30	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	0.88		0.88		0.88		ns
t_{WCKP}	WCLK Minimum Period	1.63		1.63		1.63		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		0.81		0.92		1.08	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		0.81		0.92		1.08	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-to-OUT (Pipelined)		1.32		1.51		1.77	ns
$t_{RCK2RD2}$	RCLK-to-OUT (Non-Pipelined)		2.16		2.46		2.90	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.77		0.77		0.77		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	0.93		0.93		0.93		ns
t_{RCKP}	RCLK Minimum Period	1.70		1.70		1.70		ns

Note: Timing data for this single block RAM has a depth of 4,096. For all other combinations, use Microsemi's timing software.

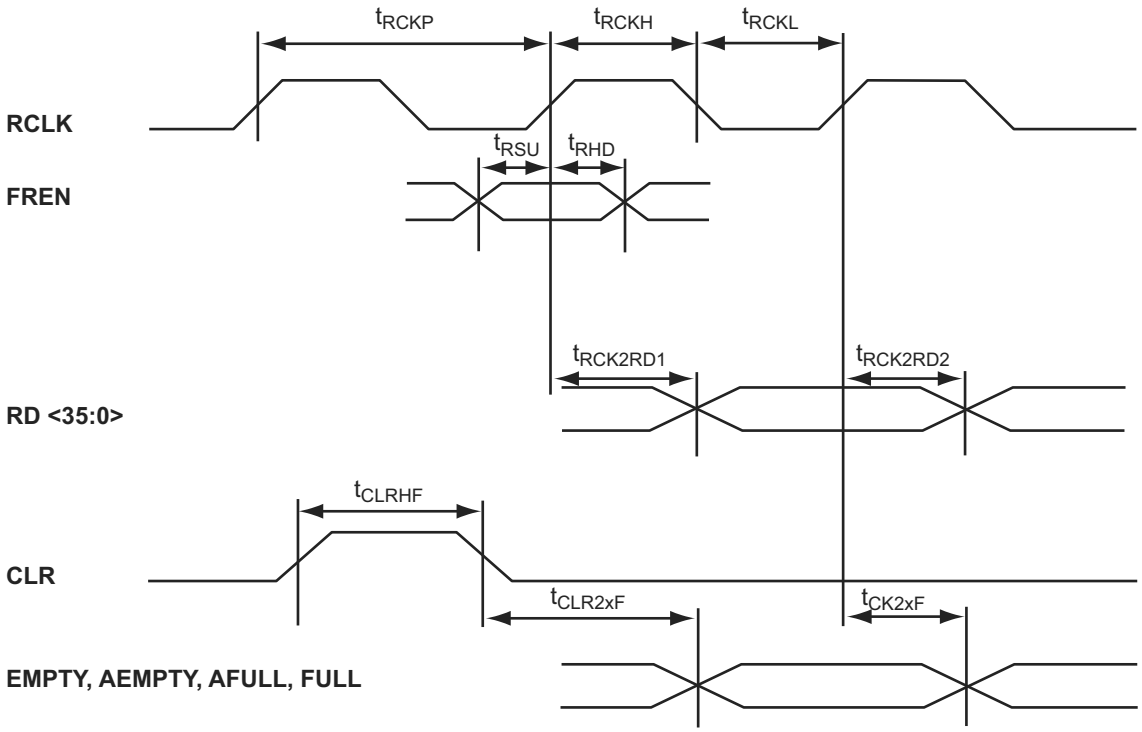


Figure 2-68 • **FIFO Read Timing**

mode if desired. Please note, if the I/O bank is not disabled, differential I/Os belonging to the I/O bank will still consume normal power, even when operating in the low power mode.

The Axcelerator device will resume normal operation 10µs after the LP pin is pulled Low.

To further reduce power consumption, the internal charge pump can be bypassed and an external power supply voltage can be used instead. This saves the internal charge-pump operating current, resulting in no DC current draw. The Axcelerator family devices have a dedicated "V_{PUMP}" pin that can be used to access an external charge pump device. In normal chip operation, when using the internal charge pump, V_{PUMP} should be tied to GND. When the voltage level on V_{PUMP} is set to 3.3V, the internal charge pump is turned off, and the V_{PUMP} voltage will be used as the charge pump voltage. Adequate voltage regulation (i.e. high drive, low output impedance, and good decoupling) should be used at V_{PUMP}.

In addition, any PLL in use can be powered down to further reduce power consumption. This can be done with the PowerDown pin driven Low. Driving this pin High restarts the PLL with the output clock(s) being stable once lock is restored.

JTAG

Axcelerator offers a JTAG interface that is compliant with the IEEE 1149.1 standard. The user can employ the JTAG interface for probing a design and performing any JTAG Public Instructions as defined in the Table 2-103.

***Table 2-103* • JTAG Instruction Code**

Instruction (IR4:IR0)	Binary Code
Extest	00000
Preload / Sample	00001
Intest	00010
USERCODE	00011
IDCODE	00100
HIGHZ	01110
CLAMP	01111
Diagnostic	10000
Reserved	All others
Bypass	11111

Interface

The interface consists of four inputs: Test Mode Select (TMS), Test Data In (TDI), Test Clock (TCK), TAP Controller Reset (TRST), and an output, Test Data Out (TDO). TMS, TDI, and TRST have on-chip pull-up resistors.

TRST

TRST (Test-Logic Reset) is an active-low, asynchronous reset signal to the TAP controller. The TRST input can be used to reset the Test Access Port (TAP) Controller to the TRST state. The TAP Controller can be held at this state permanently by grounding the TRST pin. To hold the JTAG TAP controller in the TRST state, it is recommended to connect TRST to ground via a 1 kΩ resistor.

There is an optional internal pull-up resistor available for the TRST input that can be set by the user at programming. Care should be exercised when using this option in combination with an external tie-off to ground.

An on-chip power-on-reset (POWRST) circuit is included. POWRST has the same function as "TRST," but it only occurs at power-up or during recovery from a VCCA and/or VCCDA voltage drop.

FG484	
AX500 Function	Pin Number
IO54PB2F5	H22
IO55NB2F5	L17
IO55PB2F5	K17
IO56NB2F5	K21
IO56PB2F5	K22
IO58NB2F5	L20
IO58PB2F5	K20
IO59NB2F5	L18
IO59PB2F5	K18
IO60NB2F5	M21
IO60PB2F5	L21
IO61NB2F5	L16
IO61PB2F5	K16
IO62NB2F5	M19
IO62PB2F5	L19
Bank 3	
IO63NB3F6	N16
IO63PB3F6	M16
IO64NB3F6	P22
IO64PB3F6	N22
IO65NB3F6	N20
IO65PB3F6	M20
IO66NB3F6	P21
IO66PB3F6	N21
IO67NB3F6	N18
IO67PB3F6	N19
IO68NB3F6	T22
IO68PB3F6	R22
IO69NB3F6	N17
IO69PB3F6	M17
IO70NB3F6	T21
IO70PB3F6	R21
IO71NB3F6	P18
IO71PB3F6	P19
IO72NB3F6	R20

FG484	
AX500 Function	Pin Number
IO72PB3F6	P20
IO73PB3F6	R19
IO74NB3F7	V21
IO74PB3F7	U21
IO75NB3F7	V22
IO75PB3F7	U22
IO76NB3F7	U20
IO76PB3F7	T20
IO77NB3F7	R17
IO77PB3F7	P17
IO78NB3F7	W21
IO78PB3F7	W22
IO79NB3F7	T18
IO79PB3F7	R18
IO80NB3F7	W20
IO80PB3F7	V20
IO81NB3F7	U19
IO81PB3F7	T19
IO82NB3F7	U18
IO82PB3F7	V19
IO83NB3F7	R16
IO83PB3F7	P16
Bank 4	
IO84NB4F8	AB18
IO84PB4F8	AB19
IO85NB4F8	T15
IO85PB4F8	T16
IO86NB4F8	AA18
IO86PB4F8	AA19
IO87NB4F8	W17
IO87PB4F8	V17
IO88NB4F8	Y19
IO88PB4F8	W18
IO89NB4F8	U14
IO89PB4F8	U15

FG484	
AX500 Function	Pin Number
IO90NB4F8	Y17
IO90PB4F8	Y18
IO91NB4F8	V15
IO91PB4F8	V16
IO92PB4F8	AB17
IO93NB4F8	Y15
IO93PB4F8	Y16
IO94NB4F9	AA16
IO94PB4F9	AA17
IO95NB4F9	AB14
IO95PB4F9	AB15
IO96NB4F9	W15
IO96PB4F9	W16
IO97NB4F9	AA13
IO97PB4F9	AB13
IO98NB4F9	AA14
IO98PB4F9	AA15
IO100NB4F9	Y14
IO100PB4F9	W14
IO101NB4F9	Y12
IO101PB4F9	Y13
IO102NB4F9	AA11
IO102PB4F9	AA12
IO103NB4F9/CLKEN	V12
IO103PB4F9/CLKEP	V13
IO104NB4F9/CLKFN	W11
IO104PB4F9/CLKFP	W12
Bank 5	
IO105NB5F10/CLKGN	U10
IO105PB5F10/CLKGP	U11
IO106NB5F10/CLKHN	V9
IO106PB5F10/CLKHP	V10
IO107NB5F10	Y10
IO107PB5F10	Y11
IO108NB5F10	AA9

FG484	
AX1000 Function	Pin Number
Bank 0	
IO01NB0F0	E3
IO01PB0F0	D3
IO02NB0F0	E7
IO02PB0F0	E6
IO05NB0F0	D2
IO05PB0F0	E2
IO06NB0F0	C5
IO06PB0F0	C4
IO12NB0F1	D7
IO12PB0F1	D6
IO13NB0F1	B5
IO13PB0F1	B4
IO14NB0F1	E9
IO14PB0F1	E8
IO15NB0F1	C7
IO15PB0F1	C6
IO16NB0F1	A5
IO16PB0F1	A4
IO17NB0F1	B7
IO17PB0F1	B6
IO18NB0F1	A7
IO18PB0F1	A6
IO19NB0F1	C9
IO19PB0F1	C8
IO20NB0F1	D9
IO20PB0F1	D8
IO21NB0F1	B9
IO21PB0F1	B8
IO22NB0F2	A9
IO22PB0F2	A8
IO23NB0F2	B10
IO23PB0F2	A10
IO26NB0F2	A14
IO26PB0F2	A13

FG484	
AX1000 Function	Pin Number
IO29NB0F2	B12
IO29PB0F2	B11
IO30NB0F2/HCLKAN	E11
IO30PB0F2/HCLKAP	E10
IO31NB0F2/HCLKBN	D12
IO31PB0F2/HCLKBP	D11
Bank 1	
IO32NB1F3/HCLKCN	F13
IO32PB1F3/HCLKCP	F12
IO33NB1F3/HCLKDN	E14
IO33PB1F3/HCLKDP	E13
IO34NB1F3	C13
IO34PB1F3	C12
IO37NB1F3	B14
IO37PB1F3	B13
IO38NB1F3	A16
IO38PB1F3	A15
IO40NB1F3	C15
IO42NB1F4	A18
IO42PB1F4	A17
IO43NB1F4	B16
IO43PB1F4	B15
IO44NB1F4	B18
IO44PB1F4	B17
IO45NB1F4	B19
IO45PB1F4	A19
IO46NB1F4	C19
IO46PB1F4	C18
IO48NB1F4	F15
IO48PB1F4	F14
IO49NB1F4	D16
IO49PB1F4	D15
IO50NB1F4	C17
IO50PB1F4	C16
IO51NB1F4	E22

FG484	
AX1000 Function	Pin Number
IO51PB1F4	D22
IO52NB1F4	E16
IO52PB1F4	E15
IO57NB1F5	E21
IO57PB1F5	D21
IO60NB1F5	G16
IO60PB1F5	G15
IO61NB1F5	D18
IO61PB1F5	E17
IO63NB1F5	E20
IO63PB1F5	D20
Bank 2	
IO64NB2F6	F18
IO64PB2F6	F17
IO67NB2F6	F19
IO67PB2F6	E19
IO68NB2F6	J16
IO68PB2F6	H16
IO70NB2F6	J17
IO70PB2F6	H17
IO74NB2F7	J18
IO74PB2F7	H18
IO75NB2F7	G20
IO75PB2F7	F20
IO79NB2F7	H19
IO79PB2F7	G19
IO80NB2F7	L16
IO80PB2F7	K16
IO84NB2F7	L17
IO84PB2F7	K17
IO85NB2F8	G21
IO85PB2F8	F21
IO86NB2F8	G22
IO86PB2F8	F22
IO87NB2F8	J20

FG676	
AX1000 Function	**Pin Number**
IO129PB4F12	AA21
IO131NB4F12	AD22
IO131PB4F12	AD23
IO132NB4F12	AE23
IO132PB4F12	AE24
IO133NB4F12	AB20
IO133PB4F12	AA20
IO134NB4F12	AC21
IO134PB4F12	AC22
IO135NB4F12	AF22
IO135PB4F12	AF23
IO137NB4F12	AB19
IO137PB4F12	AA19
IO139NB4F13	AC19
IO139PB4F13	AC20
IO140NB4F13	AE21
IO140PB4F13	AE22
IO141NB4F13	AD20
IO141PB4F13	AD21
IO143NB4F13	AB17
IO143PB4F13	AB18
IO144NB4F13	AE19
IO144PB4F13	AE20
IO145NB4F13	AC17
IO145PB4F13	AC18
IO146NB4F13	AD18
IO146PB4F13	AD19
IO147NB4F13	AA17
IO147PB4F13	AA18
IO148NB4F13	AF20
IO148PB4F13	AF21
IO149NB4F13	AA16
IO149PB4F13	Y16
IO151NB4F13	AC16
IO151PB4F13	AB16
IO153NB4F14	AE17

FG676	
AX1000 Function	**Pin Number**
IO153PB4F14	AE18
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AA15
IO155PB4F14	Y15
IO157NB4F14	AC15
IO157PB4F14	AB15
IO159NB4F14/CLKEN	AE16
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AE14
IO160PB4F14/CLKFP	AE15
Bank 5	
IO161NB5F15/CLKGN	AE12
IO161PB5F15/CLKGP	AE13
IO162NB5F15/CLKHN	AE11
IO162PB5F15/CLKHP	AF11
IO163NB5F15	AC12
IO163PB5F15	AB12
IO165NB5F15	Y12
IO165PB5F15	AA13
IO167NB5F15	Y11
IO167PB5F15	AA12
IO168NB5F15	AF9
IO168PB5F15	AF10
IO169NB5F15	AB11
IO169PB5F15	AA11
IO171NB5F16	AE9
IO171PB5F16	AE10
IO173NB5F16	AC10
IO173PB5F16	AC11
IO174NB5F16	AE7
IO174PB5F16	AE8
IO175NB5F16	AC9
IO175PB5F16	AD9
IO176NB5F16	AF6
IO176PB5F16	AF7

FG676	
AX1000 Function	**Pin Number**
IO177NB5F16	AA10
IO177PB5F16	AB10
IO179NB5F16	AD7
IO179PB5F16	AD8
IO180NB5F16	AC7
IO180PB5F16	AC8
IO181NB5F17	AA9
IO181PB5F17	AB9
IO183NB5F17	AD6
IO183PB5F17	AE6
IO184NB5F17	AE5
IO184PB5F17	AF5
IO185NB5F17	AA8
IO185PB5F17	AB8
IO187NB5F17	AC5
IO187PB5F17	AC6
IO188NB5F17	AD4
IO188PB5F17	AD5
IO189NB5F17	AB6
IO189PB5F17	AB7
IO190NB5F17	AF4
IO190PB5F17	AE4
IO191NB5F17	AE3
IO191PB5F17	AF3
IO192NB5F17	AA6
IO192PB5F17	AA7
Bank 6	
IO193NB6F18	Y5
IO193PB6F18	AA5
IO194NB6F18	AB3
IO194PB6F18	AC3
IO195NB6F18	Y4
IO195PB6F18	AA4
IO196NB6F18	AC2
IO196PB6F18	AD2
IO197NB6F18	W6

FG676	
AX1000 Function	**Pin Number**
GND	A8
GND	AC23
GND	AC4
GND	AD24
GND	AD3
GND	AE2
GND	AE25
GND	AF1
GND	AF13
GND	AF14
GND	AF19
GND	AF26
GND	AF8
GND	B2
GND	B25
GND	B26
GND	C24
GND	C3
GND	G20
GND	G7
GND	H1
GND	H19
GND	H26
GND	H8
GND	J18
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	K14
GND	K15
GND	K16
GND	K17
GND	L10
GND	L11

FG676	
AX1000 Function	**Pin Number**
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M10
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N1
GND	N10
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N26
GND	P1
GND	P10
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P26
GND	R10
GND	R11

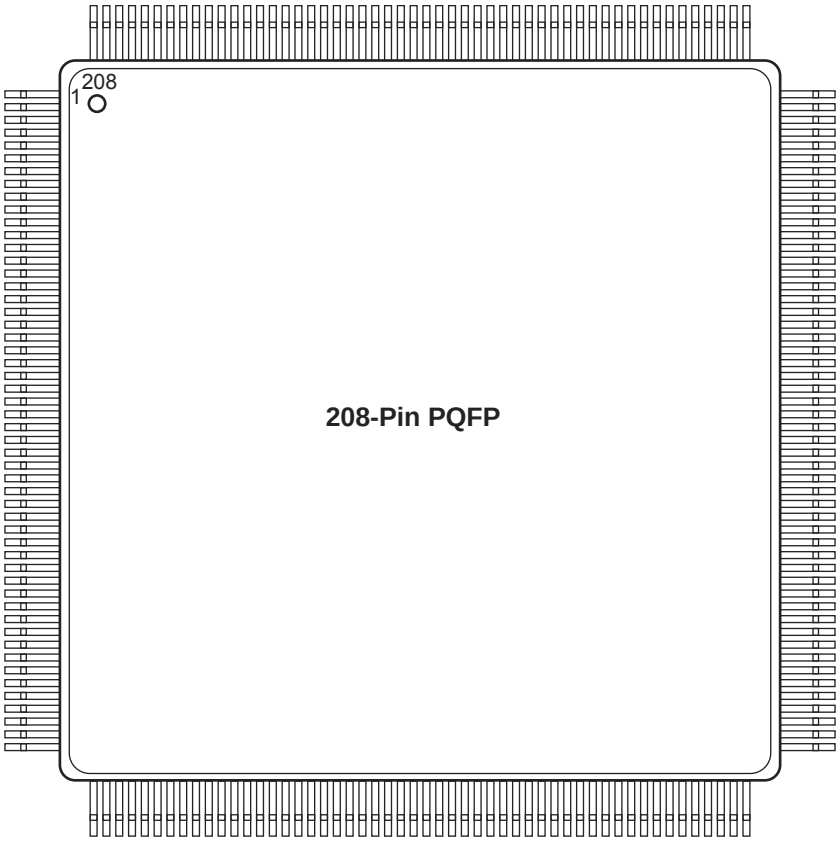
FG676	
AX1000 Function	**Pin Number**
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A25
NC	AC13
NC	AC14
NC	AF2
NC	AF25

FG1152	
AX2000 Function	Pin Number
GND	AK12
GND	AK17
GND	AK18
GND	AK23
GND	AK30
GND	AK5
GND	AL1
GND	AL11
GND	AL2
GND	AL24
GND	AL3
GND	AL31
GND	AL32
GND	AL33
GND	AL34
GND	AL4
GND	AM1
GND	AM10
GND	AM15
GND	AM2
GND	AM20
GND	AM25
GND	AM3
GND	AM31
GND	AM32
GND	AM33
GND	AM34
GND	AM4
GND	AN1
GND	AN2
GND	AN26
GND	AN3
GND	AN31
GND	AN32
GND	AN33

FG1152	
AX2000 Function	Pin Number
GND	AN34
GND	AN4
GND	AN9
GND	AP13
GND	AP2
GND	AP22
GND	AP27
GND	AP3
GND	AP31
GND	AP32
GND	AP33
GND	AP4
GND	AP8
GND	B1
GND	B2
GND	B26
GND	B3
GND	B31
GND	B32
GND	B33
GND	B34
GND	B4
GND	B9
GND	C1
GND	C10
GND	C15
GND	C2
GND	C20
GND	C25
GND	C3
GND	C31
GND	C32
GND	C33
GND	C34
GND	C4

FG1152	
AX2000 Function	Pin Number
GND	D1
GND	D11
GND	D2
GND	D24
GND	D3
GND	D31
GND	D32
GND	D33
GND	D34
GND	D4
GND	E12
GND	E17
GND	E18
GND	E23
GND	E30
GND	E5
GND	F29
GND	F30
GND	F6
GND	G28
GND	G7
GND	H1
GND	H34
GND	J2
GND	J33
GND	K3
GND	K32
GND	L11
GND	L24
GND	L31
GND	L4
GND	M12
GND	M23
GND	M30
GND	M5

PQ208



Note

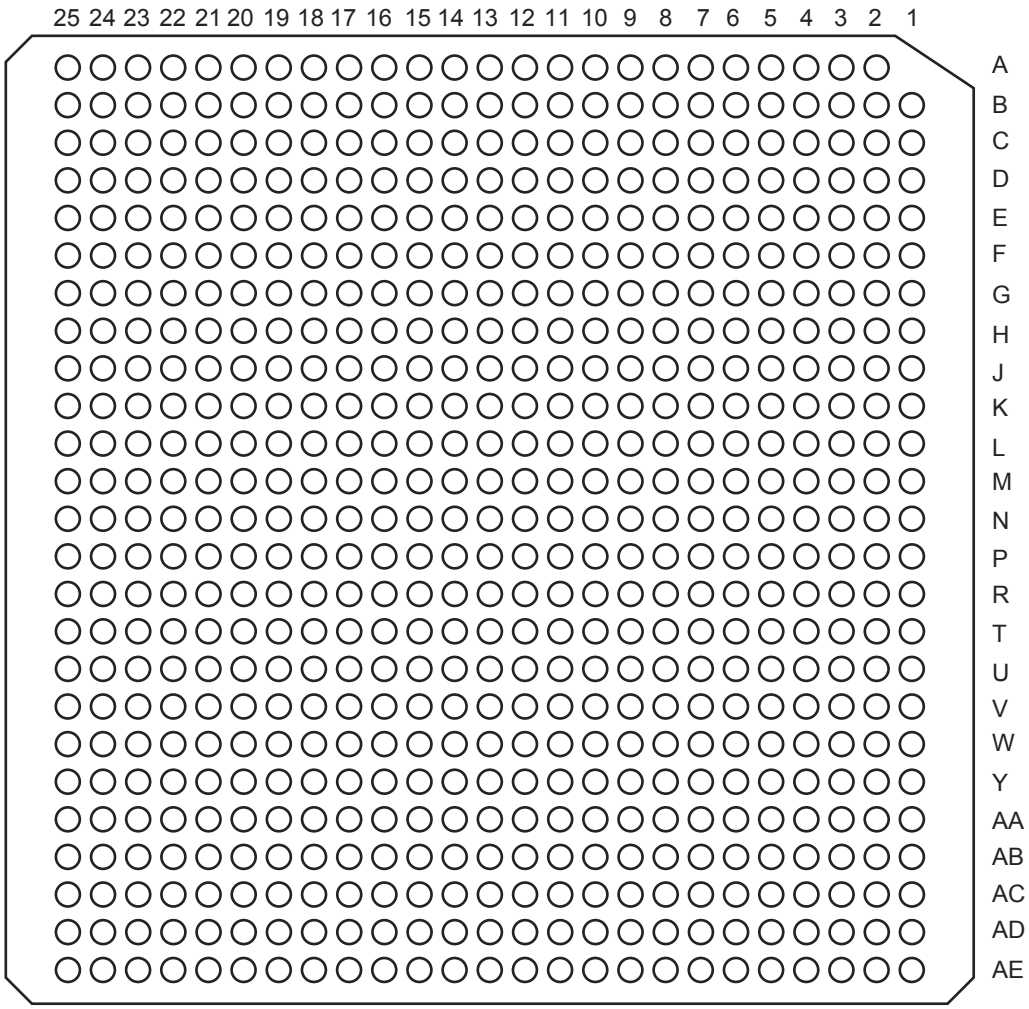
For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CQ352	
AX250 Function	Pin Number
Bank 0	
IO00NB0F0	341
IO00PB0F0	342
IO01NB0F0	343
IO02NB0F0	337
IO02PB0F0	338
IO04NB0F0	335
IO04PB0F0	336
IO06NB0F0	331
IO06PB0F0	332
IO08NB0F0	325
IO08PB0F0	326
IO10NB0F0	323
IO10PB0F0	324
IO12NB0F0/HCLKAN	319
IO12PB0F0/HCLKAP	320
IO13NB0F0/HCLKBN	313
IO13PB0F0/HCLKBP	314
Bank 1	
IO14NB1F1/HCLKCN	305
IO14PB1F1/HCLKCP	306
IO15NB1F1/HCLKDN	299
IO15PB1F1/HCLKDP	300
IO16NB1F1	289
IO16PB1F1	290
IO17NB1F1	295
IO17PB1F1	296
IO18NB1F1	287
IO18PB1F1	288
IO20NB1F1	283
IO20PB1F1	284
IO22NB1F1	277
IO22PB1F1	278
IO23NB1F1	281
IO23PB1F1	282

CQ352	
AX250 Function	Pin Number
IO24NB1F1	275
IO24PB1F1	276
IO25NB1F1	271
IO25PB1F1	272
IO27NB1F1	269
IO27PB1F1	270
Bank 2	
IO29NB2F2	261
IO29PB2F2	262
IO30NB2F2	259
IO30PB2F2	260
IO31NB2F2	255
IO31PB2F2	256
IO33NB2F2	249
IO33PB2F2	250
IO34NB2F2	253
IO34PB2F2	254
IO35NB2F2	247
IO35PB2F2	248
IO36NB2F2	243
IO36PB2F2	244
IO37NB2F2	241
IO37PB2F2	242
IO38NB2F2	237
IO38PB2F2	238
IO39NB2F2	235
IO39PB2F2	236
IO41NB2F2	231
IO41PB2F2	232
IO42NB2F2	229
IO42PB2F2	230
IO43NB2F2	225
IO43PB2F2	226
IO44NB2F2	223
IO44PB2F2	224

CQ352	
AX250 Function	Pin Number
Bank 3	
IO45NB3F3	217
IO45PB3F3	218
IO46NB3F3	219
IO46PB3F3	220
IO47NB3F3	213
IO47PB3F3	214
IO48NB3F3	211
IO48PB3F3	212
IO49NB3F3	207
IO49PB3F3	208
IO51NB3F3	205
IO51PB3F3	206
IO52NB3F3	201
IO52PB3F3	202
IO53NB3F3	199
IO53PB3F3	200
IO54NB3F3	195
IO54PB3F3	196
IO55NB3F3	193
IO55PB3F3	194
IO56NB3F3	187
IO56PB3F3	188
IO57NB3F3	189
IO57PB3F3	190
IO59NB3F3	183
IO59PB3F3	184
IO60NB3F3	181
IO60PB3F3	182
IO61NB3F3	179
IO61PB3F3	180
Bank 4	
IO62NB4F4	172
IO62PB4F4	173
IO64NB4F4	166

CG624



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CG624	
AX2000 Function	**Pin Number**
IO229PB5F21	AD10
IO230NB5F21	V11
IO233NB5F21	AD7
IO233PB5F21	AD8
IO234NB5F21	V9
IO234PB5F21	V10
IO236NB5F22	AC9
IO238NB5F22	W8
IO238PB5F22	W9
IO239NB5F22	AE4
IO239PB5F22	AE5
IO240NB5F22	AB9
IO242NB5F22	AA9
IO242PB5F22	Y9
IO243NB5F22	AD5
IO243PB5F22	AD6
IO244NB5F22	U8
IO246NB5F23	AB8
IO246PB5F23	AC8
IO247NB5F23	AB7
IO247PB5F23	AC7
IO250NB5F23	AA8
IO250PB5F23	Y8
IO251NB5F23	V8
IO251PB5F23	V7
IO252NB5F23	Y7
IO252PB5F23	W7
IO253NB5F23	AC5
IO253PB5F23	AC6
IO254NB5F23	Y6
IO254PB5F23	W6
IO256NB5F23	AB6*

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO256PB5F23	AA6*
Bank 6	
IO257NB6F24	Y3
IO257PB6F24	AA3
IO258NB6F24	V3
IO258PB6F24	W3
IO259NB6F24	AA2
IO259PB6F24	AB2
IO260NB6F24	V6*
IO260PB6F24	W4*
IO262NB6F24	U4
IO262PB6F24	V4
IO263NB6F24	Y5
IO263PB6F24	W5
IO268NB6F25	U6
IO268PB6F25	U5
IO269PB6F25	U3
IO272NB6F25	T2
IO272PB6F25	U2
IO273NB6F25	W2
IO273PB6F25	Y2
IO274NB6F25	R6
IO274PB6F25	T6
IO275NB6F25	T7
IO275PB6F25	U7
IO277NB6F25	V2
IO278NB6F26	R4
IO278PB6F26	T4
IO279PB6F26	R3
IO280NB6F26	R5
IO281NB6F26	AA1
IO281PB6F26	AB1

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO284NB6F26	R8
IO284PB6F26	T8
IO285NB6F26	W1
IO285PB6F26	Y1
IO286NB6F26	P2
IO286PB6F26	R2
IO287NB6F26	T1
IO287PB6F26	U1
IO288NB6F26	P5
IO290NB6F27	P6
IO291NB6F27	P1
IO291PB6F27	R1
IO292NB6F27	P7
IO292PB6F27	R7
IO293NB6F27	M1
IO293PB6F27	N1
IO294NB6F27	P8
IO296NB6F27	N3
IO296PB6F27	P3
IO298NB6F27	N4
IO298PB6F27	P4
IO299NB6F27	M2
IO299PB6F27	N2
Bank 7	
IO300NB7F28	P9*
IO300PB7F28	N6*
IO302NB7F28	M6
IO304NB7F28	N8
IO304PB7F28	N7
IO308NB7F28	M4
IO309NB7F28	L3
IO309PB7F28	M3

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

4 – Datasheet Information

List of Changes

The following table lists critical changes that were made in the current version of the document.

Revision	Changes	Page
Revision 18 (March 2012)	Table 2-1 • Absolute Maximum Ratings was updated to correct the maximum DC core supply voltage (VCCA) from 1.6 V to 1.7 V (SAR 36786). The maximum input voltage (VI) was corrected from 3.75 V to 4.1 V (SAR 35419).	2-1
	Values for tristate leakage current IOZ, and IIH and IIL were added to Table 2-3 • Standby Current (SARs 35774, 32021).	2-2
	Figure 2-2 • VCCPLX and VCOMPLX Power Supply Connect was updated to correct the units for the resistance from "W" to Ω (SAR 36415).	2-9
	In the Introduction to the "User I/Os" section, the following sentence was added to clarify the slew rate setting (SAR 34943): The slew rate setting is effective for both rising and falling edges.	2-11
	Figure 2-3 • Use of an External Resistor for 5 V Tolerance was revised to show the VCCI and GND clamp diodes. The explanatory text above the figure was revised as well (SAR 34942).	2-13
	EQ 3 for 5 V tolerance was corrected to change Vdiode from 0.6 V to 0.7 V (SAR 36786).	2-13
	Additional information was added to the "Using the Weak Pull-Up and Pull-Down Circuits" section to clarify how the weak pull-up and pull-down resistors are physically implemented (SAR 34945).	2-17
	The description for the C_{INCLK} parameter in Table 2-18 • Input Capacitance was changed from "Input capacitance on clock pin" to "Input capacitance on HCLK and RCLK pin" (SAR 34944).	2-21
	Table 2-19 • I/O Input Rise Time and Fall Time* is new (SAR 34942).	2-21
	The minimum VIL for 1.5 V LVCMOS and PCI was corrected from –0.5 to –0.3 in Table 2-29 • DC Input and Output Levels and Table 2-33 • DC Input and Output Levels (SAR 34358).	2-38, 2-40
	Support for simulating the GCLR/ GPSET feature in the Axcelerator Family was added in Libero software v9.0 SPI1. Reference to the section explaining this in the *Antifuse Macro Library Guide* was added to the "R-Cell" section (SAR 26413).	2-58
	The enable signal in Figure 2-32 • R-Cell Delays was corrected to show it is active low rather than active high (SAR 34946).	2-59
Revision 17 (September 2011)	The versioning system for datasheets has been changed. Datasheets are assigned a revision number that increments each time the datasheet is revised. The "Axcelerator Family Device Status" table indicates the status for each device in the device family.	iii
	The "Features" section, "Programmable Interconnect Element" section, and "Security" section were revised to clarify that although no existing security measures can give an absolute guarantee, Microsemi FPGAs implement the best security available in the industry (SAR 32865).	i, 1-1, 2-108